

# CY74FCT16841T CY74FCT162841T

# 20-Bit Latches

SCCS067A - July 1994 - Revised October 2001

### Features

- FCT-C speed at 5.5 ns (FCT16841T Com'l)
- I<sub>off</sub> supports partial-power-down mode operation
- Edge-rate control circuitry for significantly improved noise characteristics
- Typical output skew < 250 ps
- ESD > 2000V
- TSSOP (19.6-mil pitch) and SSOP (25-mil pitch) packages
- Industrial temperature range of -40°C to +85°C
- $V_{CC}$  = 5V  $\pm$  10%

CY74FCT16841T Features:

- 64 mA sink current, 32 mA source current
- Typical V<sub>OLP</sub> (ground bounce) <1.0V at V<sub>CC</sub> = 5V,  $T_A = 25^{\circ}C$

#### CY74FCT162841T Features:

- Balanced 24 mA output drivers
- Reduced system switching noise
- Typical V<sub>OLP</sub> (ground bounce) <0.6V at V<sub>CC</sub> = 5V,  $T_{A}$ = 25 $^{\circ}C$

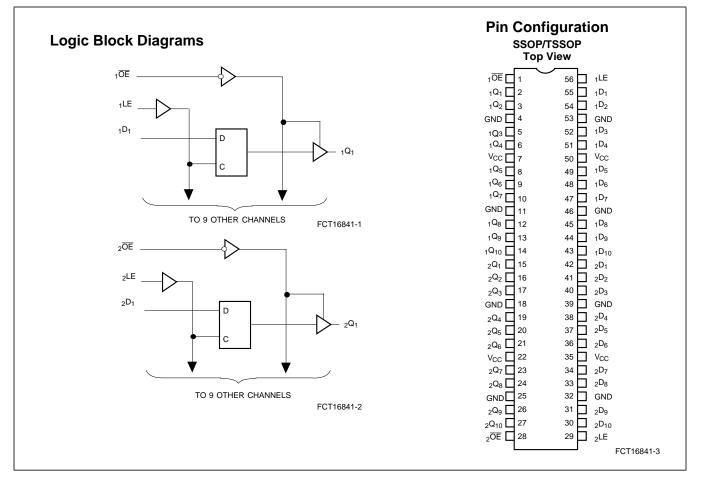
### **Functional Description**

The CY74FCT16841T and CY74FCT162841T are 20-bit D-type latches designed for use in bus applications requiring high speed and low power. These devices can be used as two independent 10-bit latches, or as a single 10-bit latch, or as a single 20-bit latch by connecting the Output Enable ( $\overline{OE}$ ) and Latch (LE) inputs. Flow-through pinout and small shrink packaging aid in simplifying board layout.

This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

The CY74FCT16841T is ideally suited for driving high-capacitance loads and low-impedance backplanes.

The CY74FCT162841T has 24-mA balanced output drivers with current limiting resistors in the outputs. This reduces the need for external terminating resistors and provides for minimal undershoot and reduced ground bounce. The CY74FCT162841T is ideal for driving transmission lines.





## **Pin Description**

Name	Description		
D	Data Inputs		
LE Latch Enable Input (Active HIGH)			
ŌĒ	Output Enable Input (Active LOW)		
0	Three-State Outputs		

## Maximum Ratings<sup>[3, 4]</sup>

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature	–55°C to +125°C
Ambient Temperature with Power Applied	–55°C to +125°C
DC Input Voltage	–0.5V to +7.0V
DC Output Voltage	–0.5V to +7.0V
DC Output Current (Maximum Sink Current/Pin)	–60 to +120 mA

#### Electrical Characteristics Over the Operating Range

### Function Table<sup>[1]</sup>

	Inputs		Outputs
D	LE	ŌĒ	Q
Н	Н	L	Н
L	Н	L	L
Х	L	L	Q <sup>[2]</sup>
Х	Х	Н	Z

Power Dissipation	1.0W
Static Discharge Voltage	>2001V
(per MIL-STD-883, Method 3015)	

### **Operating Range**

Range	Ambient Temperature	v <sub>cc</sub>
Industrial	–40°C to +85°C	5V ± 10%

Parameter	Description	Test Conditions	Min.	<b>Typ.</b> <sup>[5]</sup>	Max.	Unit
V <sub>IH</sub>	Input HIGH Voltage	Logic HIGH Level	2.0			V
V <sub>IL</sub>	Input LOW Voltage	Logic LOW Level			0.8	V
V <sub>H</sub>	Input Hysteresis <sup>[6]</sup>			100		mV
V <sub>IK</sub>	Input Clamp Diode Voltage	V <sub>CC</sub> =Min., I <sub>IN</sub> =-18 mA		-0.7	-1.2	V
I <sub>IH</sub>	Input HIGH Current	V <sub>CC</sub> =Max., V <sub>I</sub> =V <sub>CC</sub>			±1	μA
IIL	Input LOW Current	V <sub>CC</sub> =Max., V <sub>I</sub> =GND			±1	μA
I <sub>OZH</sub>	High Impedance Output Current (Three-State Output pins)	V <sub>CC</sub> =Max., V <sub>OUT</sub> =2.7V			±1	μA
I <sub>OZL</sub>	High Impedance Output Current (Three-State Output pins)	V <sub>CC</sub> =Max., V <sub>OUT</sub> =0.5V			±1	μA
I <sub>OS</sub>	Short Circuit Current <sup>[7]</sup>	V <sub>CC</sub> =Max., V <sub>OUT</sub> =GND	-80	-140	-200	mA
Ι <sub>Ο</sub>	Output Drive Current <sup>[7]</sup>	V <sub>CC</sub> =Max., V <sub>OUT</sub> =2.5V	-50		-180	mA
I <sub>OFF</sub>	Power-Off Disable	V <sub>CC</sub> =0V, V <sub>OUT</sub> ≤4.5V <sup>[8]</sup>			±1	μA

Notes:

1.

2. 3.

H = HIGH Voltage Level. L = LOW Voltage Level. X = Don't Care. Z = HIGH Impedance. Output level before LE HIGH-to-LOW Transition. Operation beyond the limits set forth may impair the useful life of the device. Unless otherwise noted, these limits are over the operating free-air temperature range.

4. Unused inputs must always be connected to an appropriate logic voltage level, preferably either V<sub>CC</sub> or ground.

Typical values are at  $V_{CC}$ = 5.0V,  $T_A$ = +25°C ambient. This parameter is specified but not tested. 5.

6. 7.

Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample and hold techniques are preferable in order to minimize internal chip heating and more accurately reflect operational values. Otherwise prolonged shorting of a high output may raise the chip temperature well above normal and thereby cause invalid readings in other parametric tests. In any sequence of parameter tests, I<sub>OS</sub> tests should be performed last.

8. Tested at +25°C.



### **Output Drive Characteristics for CY74FCT16841T**

Parameter	Description	Test Conditions	Min.	<b>Typ.</b> <sup>[5]</sup>	Max.	Unit
V <sub>OH</sub>	Output HIGH Voltage	V <sub>CC</sub> =Min., I <sub>OH</sub> =-3 mA	2.5	3.5		V
		V <sub>CC</sub> =Min., I <sub>OH</sub> =-15 mA	2.4	3.5		
		V <sub>CC</sub> =Min., I <sub>OH</sub> =-32 mA	2.0	3.0		
V <sub>OL</sub>	Output LOW Voltage	V <sub>CC</sub> =Min., I <sub>OL</sub> =64 mA		0.2	0.55	V

### **Output Drive Characteristics for CY74FCT162841T**

Parameter	Description	Test Conditions	Min.	<b>Typ.</b> <sup>[5]</sup>	Max.	Unit
I <sub>ODL</sub>	Output LOW Current <sup>[7]</sup>	$V_{CC}$ =5V, $V_{IN}$ =V <sub>IH</sub> or $V_{IL}$ , $V_{OUT}$ =1.5V	60	115	150	mA
I <sub>ODH</sub>	Output HIGH Current <sup>[7]</sup>	$V_{CC}$ =5V, $V_{IN}$ =V <sub>IH</sub> or $V_{IL}$ , $V_{OUT}$ =1.5V	-60	–115	-150	mA
V <sub>OH</sub>	Output HIGH Voltage	V <sub>CC</sub> =Min., I <sub>OH</sub> =-24 mA	2.4	3.3		V
V <sub>OL</sub>	Output LOW Voltage	V <sub>CC</sub> =Min., I <sub>OL</sub> =24 mA		0.3	0.55	V

## **Capacitance**<sup>[6]</sup> (T<sub>A</sub> =+25°C, f = 1.0 MHz)

Symbol	Description	Conditions	<b>Typ.</b> <sup>[5]</sup>	Max.	Unit
C <sub>IN</sub>	Input Capacitance	$V_{IN} = 0V$	4.5	6.0	pF
C <sub>OUT</sub>	Output Capacitance	V <sub>OUT</sub> = 0V	5.5	8.0	pF

### **Power Supply Characteristics**

Parameter	Description	Test Condit	ions	Min.	<b>Typ.</b> <sup>[5]</sup>	Max.	Unit
I <sub>CC</sub>	Quiescent Power Supply Current	V <sub>CC</sub> =Max.	V <sub>IN</sub> ≤0.2V V <sub>IN</sub> ≥V <sub>CC</sub> -0.2V	—	5	500	μΑ
ΔI <sub>CC</sub>	Quiescent Power Supply Current (TTL inputs HIGH)	V <sub>CC</sub> =Max.,	V <sub>IN</sub> =3.4V <sup>[9]</sup>	—	0.5	1.5	mA
I <sub>CCD</sub>	Dynamic Power Supply Current <sup>[10]</sup>	V <sub>CC</sub> =Max., One Input Toggling, 50% Duty Cycle, Outputs Open, OE=GND	V <sub>IN</sub> =V <sub>CC</sub> or V <sub>IN</sub> =GND	_	60	100	μA/MHz
Ι <sub>C</sub>	Total Power Supply Current <sup>[11]</sup>	50% Duty Cycle, Outputs Open, One Bit	V <sub>IN</sub> =V <sub>CC</sub> or V <sub>IN</sub> =GND	—	0.6	1.5	mA
			V <sub>IN</sub> =3.4V or V <sub>IN</sub> =GND	—	0.9	2.3	
		V <sub>CC</sub> =Max., f <sub>1</sub> =2.5 MHz, 50% Duty Cycle, Outputs	V <sub>IN</sub> =V <sub>CC</sub> or V <sub>IN</sub> =GND	—	3.0	5.5 <sup>[12]</sup>	
		Open, Tw <u>enty</u> Bits Toggling, OE=GND LE = V <sub>CC</sub>	V <sub>IN</sub> =3.4V or V <sub>IN</sub> =GND	—	8.0	20.5 <sup>[12]</sup>	

#### Notes:

9. Per TTL driven input (V<sub>IN</sub>=3.4V); all other inputs at V<sub>CC</sub> or GND. 10. This parameter is not directly testable, but is derived for use in Total Power Supply calculations. 11.  $I_C = I_{OUIESCENT} + I_{INPUTS} + I_{DYNAMIC}$   $I_C = I_{CC} + \Delta I_{CC} D_H N_T + I_{CCD} (f_0/2 + f_1 N_1)$   $I_{CC} = Quiescent Current with CMOS input levels$ 



## Switching Characteristics Over the Operating Range<sup>[13]</sup>

			74FCT1	6841AT	74FCT1 74FCT16			Fig
Parameter	Description	Condition <sup>[14]</sup>	Min.	Max.	Min.	Max.	Unit	Fig. No. <sup>[15]</sup>
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation Delay D to Q	C <sub>L</sub> =50 pF R <sub>L</sub> =500Ω	1.5	9.0	1.5	5.5	ns	1, 5
	(LE=HIGH)	C <sub>L</sub> =300 pF <sup>[16]</sup> R <sub>L</sub> =500Ω	1.5	13.0	1.5	13.0		
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation Delay LE to Q	C <sub>L</sub> =50 pF R <sub>L</sub> =500Ω	1.5	12.0	1.5	6.4	ns	1, 5
		C <sub>L</sub> =300 pF <sup>[16]</sup> R <sub>L</sub> =500Ω	1.5	16.0	1.5	15.0		
t <sub>PHZ</sub> t <sub>PZL</sub>	Output Enable Time OE to Q	C <sub>L</sub> =50 pF R <sub>L</sub> =500Ω	1.5	11.5	1.5	6.5	ns	1, 7, 8
		C <sub>L</sub> =300 pF <sup>[16]</sup> R <sub>L</sub> =500Ω	1.5	23.0	1.5	12.0		
t <sub>PHZ</sub> t <sub>PLZ</sub>	Output Disable Time OE to Q	C <sub>L</sub> =5 pF <sup>[16]</sup> R <sub>L</sub> =500Ω	1.5	7.0	1.5	5.7	ns	1, 7, 8
		C <sub>L</sub> =50 pF R <sub>L</sub> =500Ω	1.5	8.0	1.5	6.0		
t <sub>SU</sub>	Set-Up Time HIGH or LOW, D to LE	C <sub>L</sub> =50 pF R <sub>L</sub> =500Ω	2.5	—	2.0	—	ns	9
t <sub>H</sub>	Hold Time HIGH or LOW, D to LE		2.5	_	1.5	—	ns	9
t <sub>W</sub>	LE Pulse Width HIGH		4.0 <sup>[17]</sup>	—	4.0 <sup>[17]</sup>	—	ns	5
t <sub>SK(O)</sub>	Output Skew <sup>[18]</sup>		—	0.5		0.5	ns	—

Notes:

Minimum limits are specified but not tested on Propagation Delays.
See test circuit and waveform.
See "Parameter Measurement Information" in the General Information section.
These conditions are specified but not tested.
These limits are specified but not tested.
Skew between any two outputs of the same package switching in the same direction. This parameter is ensured by design.

## Ordering Information for CY74FCT16841T

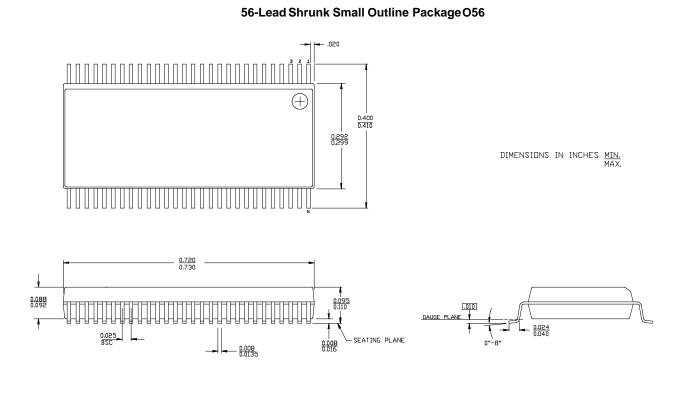
Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
5.5	CY74FCT16841CTPVC/PVCT	O56	56-Lead (300-Mil) SSOP	Industrial
6.5	CY74FCT16841ATPVC/PVCT	O56	56-Lead (300-Mil) SSOP	Industrial

## Ordering Information CY74FCT162841T

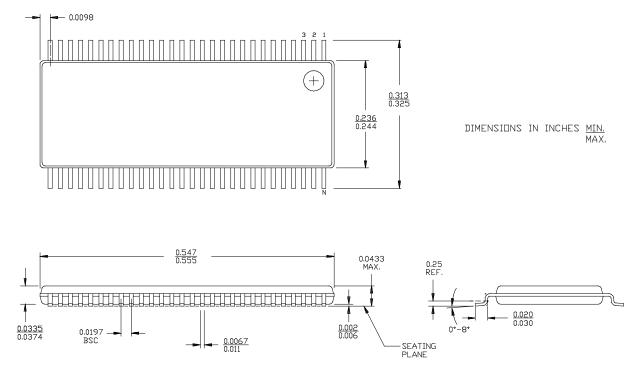
Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
5.5	74FCT162841CTPACT	Z56	56-Lead (240-Mil) TSSOP	Industrial
	CY74FCT162841CTPVC	O56	56-Lead (300-Mil) SSOP	
	74FCT162841CTPVCT	O56	56-Lead (300-Mil) SSOP	



## Package Diagrams



#### 56-Lead Thin Shrunk Small Outline Package Z56



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11-Nov-2009

#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
74FCT162841CTPACT	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74FCT162841CTPVCG4	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74FCT162841CTPVCT	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74FCT162841ETPVCT	OBSOLETE	SSOP	DL	56		TBD	Call TI	Call TI
74FCT16841ATPVCG4	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74FCT16841CTPVCG4	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74FCT16841CTPVCTG4	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT162841CTPVC	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT162841ETPVC	OBSOLETE	SSOP	DL	56		TBD	Call TI	Call TI
CY74FCT16841ATPVC	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT16841CTPVC	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT16841CTPVCT	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
FCT162841CTPACTE4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
FCT162841CTPACTG4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
FCT162841CTPVCTG4	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

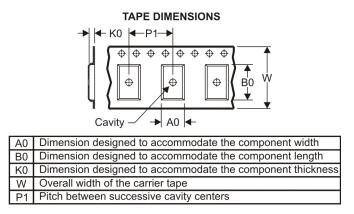
# PACKAGE MATERIALS INFORMATION

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Texas Instruments

### TAPE AND REEL INFORMATION





### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



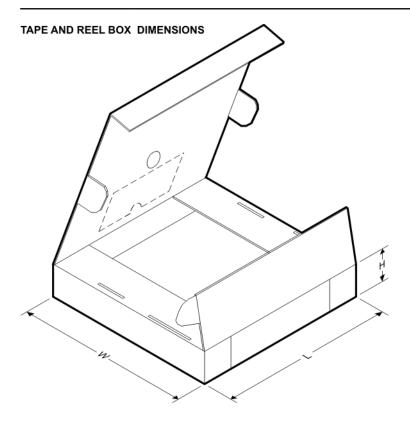
All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74FCT162841CTPACT	TSSOP	DGG	56	2000	330.0	24.4	8.6	15.6	1.8	12.0	24.0	Q1
74FCT162841CTPVCT	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1
CY74FCT16841CTPVCT	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1

TEXAS INSTRUMENTS

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# PACKAGE MATERIALS INFORMATION

29-Jul-2009



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74FCT162841CTPACT	TSSOP	DGG	56	2000	346.0	346.0	41.0
74FCT162841CTPVCT	SSOP	DL	56	1000	346.0	346.0	49.0
CY74FCT16841CTPVCT	SSOP	DL	56	1000	346.0	346.0	49.0

MSSO001C - JANUARY 1995 - REVISED DECEMBER 2001

#### PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN

DL (R-PDSO-G\*\*)



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MO-118



MTSS003D - JANUARY 1995 - REVISED JANUARY 1998

#### DGG (R-PDSO-G\*\*)

#### PLASTIC SMALL-OUTLINE PACKAGE

**48 PINS SHOWN** 



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153





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### **PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
74FCT162841CTPACT	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
74FCT162841CTPVCG4	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
74FCT162841ETPVCT	OBSOLETE	SSOP	DL	56		TBD	Call TI	Call TI	Samples Not Available
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CY74FCT162841CTPVC	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CY74FCT162841ETPVC	OBSOLETE	SSOP	DL	56		TBD	Call TI	Call TI	Samples Not Available
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CY74FCT16841CTPVC	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
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<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

## PACKAGE OPTION ADDENDUM



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**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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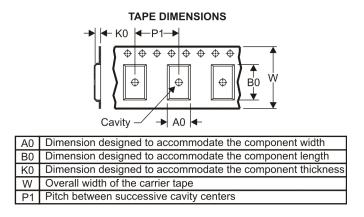
# PACKAGE MATERIALS INFORMATION

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### TAPE AND REEL INFORMATION





## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74FCT162841CTPACT	TSSOP	DGG	56	2000	330.0	24.4	8.6	15.6	1.8	12.0	24.0	Q1
CY74FCT16841CTPVCT	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1

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# PACKAGE MATERIALS INFORMATION

23-Jul-2010



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74FCT162841CTPACT	TSSOP	DGG	56	2000	346.0	346.0	41.0
CY74FCT16841CTPVCT	SSOP	DL	56	1000	346.0	346.0	49.0

MSSO001C - JANUARY 1995 - REVISED DECEMBER 2001

#### PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN

DL (R-PDSO-G\*\*)



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MO-118



MTSS003D - JANUARY 1995 - REVISED JANUARY 1998

#### DGG (R-PDSO-G\*\*)

#### PLASTIC SMALL-OUTLINE PACKAGE

**48 PINS SHOWN** 



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



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